

REMARKS

In the above-identified Office Action claims 1, 2 and 4 have been rejected as anticipated by Stewart et al. Applicant has amended Claim 1 so that it now defines over Stewart et al. in that there is now recited the method step of placing the adhesive sheet on the wiring pattern so as to leave a space between the adhesive sheet and the printed circuit board. There is no spacing shown on Stewart et al. and, thus, there can be no method step of placing the adhesive sheet on the printed circuit board so as to leave a space there between. This is critical in the invention insofar as it is the spacing, which contains the air which is heated so as to heat the adhesive sheet to bond to the printed circuit board. Without the spacing, Stewart et al, cannot be said to teach the subject method steps.

Claims 2 and 4, being dependent upon Claim 1, also should be patentable for the same reasons.

Claim 3 has been rejected as unpatentable over Stewart et al. in view of Kumakura, however neither Stewart et al. nor Kumakura teach the spacing between the adhesive sheet and the printed circuit board and, accordingly, cannot make obvious the subject invention as in Claim 3.

Claim 5 has been rejected as unpatentable over Stewart et al. in view of Kumakura. While the Examiner has referred to Claim 4 in the final sentence of the first full paragraph of page 3 in the Office Action, Applicant assumes that he refers to Claim 5. Insofar as Claim 5 depends upon Claim 1, which recites that the step of placing an adhesive sheet on the wiring pad so as to leave a space between the adhesive sheet and the printed circuit board. Neither the spacing or the step of forming the spacing is taught in either Kumakura or Stewart et al. Applicant believes that Claim 5 is now allowable.

The Examiner has also rejected claims 5 and 6 in view of Applicant's admitted prior art. However, the admitted prior art does not include the spacing referred to above nor the manner of placing the adhesive sheet on the patterned circuit board so as to form the spacing and, accordingly, Applicant believes claims 5 and 6 are allowable.

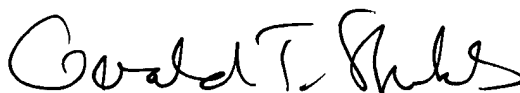
Stewart et al. teaches, in Figure 8, an integrated circuit connected indirectly to an array of solder bumps within an interconnecting matrix. The thermal plastic adhesive 7 is attached to an available surface on the surface of the connecting substrate. Thus the thermo plastic adhesive is already in place on the substrate, where the surface mounted electronic device is to be placed and secured. As stated, in paragraph 90 of Stewart et al., generally speaking, air convection heat from heaters, vapor phase and laser scanning technologies can be used to heat the solder as well as the thermo plastic adhesive. There is no suggestion that the air between the adhesive sheet and the printed circuit board be heated; rather it would appear that the exterior of the assembly is heated such as by placing in an oven. Thus, Stewart et al. teaches placing the adhesive directly on the circuit board while the subject invention involves an adhesive sheet which is placed over the circuit board so as to create a space between the adhesive sheet and the circuit board. As stated above, this is not taught by Stewart et al., Kumakura or Applicant's admitted prior art.

Applicant hereby requests reconsideration and reexamination thereof.

With the above amendments and remarks, this application is considered ready for allowance and applicant earnestly solicits an early notice of same. Should the Examiner be of the opinion that a telephone conference would expedite prosecution of the subject application, he is respectfully requested to call the undersigned at the below listed number.

US 10/560,849

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Gerald T. Shekleton". The signature is fluid and cursive, with the first name "Gerald" being more prominent than the last name "Shekleton".

Dated: 3 September 2008

Gerald T Shekleton

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